PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT6805752

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
JAEYOUNG CHOI	03/30/2021
DEOK HOE KIM	03/29/2021
KYU HWAN KIM	03/29/2021
CHAE KWANG LEE	03/29/2021
JANE JUNG LEE	03/29/2021
JUCHANG LEE	03/30/2021

RECEIVING PARTY DATA

Name:	SAP SE
Street Address:	DIETMAR-HOPP-ALLEE 16
City:	WALLDORF
State/Country:	GERMANY
Postal Code:	D-69190

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	17217412

CORRESPONDENCE DATA

Fax Number: (503)595-5301

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 503-595-5300
Email: kelly.mccarthy@klarquist.com
Correspondent Name: CORY A. JONES, KLARQUIST SPARKMAN, LLP
Address Line 1: 121 S.W. SALMON STREET, SUITE 1600
Address Line 2: ONE WORLD TRADE CENTER
Address Line 4: PORTLAND, OREGON 97204

ATTORNEY DOCKET NUMBER:	8880-105854-01
NAME OF SUBMITTER:	CORY A. JONES
SIGNATURE:	/Cory A. Jones/
DATE SIGNED:	07/09/2021

Total Attachments: 6

source=Assignments-105854-01#page1.tif
source=Assignments-105854-01#page2.tif
source=Assignments-105854-01#page3.tif
source=Assignments-105854-01#page4.tif
source=Assignments-105854-01#page5.tif
source=Assignments-105854-01#page6.tif

Attorney Dkt. No. 8880-105854-01 / 200879US01

ASSIGNMENT

For valuable consideration, I, **Jaeyoung Choi,**

hereby assign to

SAP SE, a corporation of Europe having a place of business at Dietmar-Hopp-Allee 16, 69190 Walldorf, Germany

and its successors, and assigns (collectively, the ASSIGNEE) my entire right, title and interest throughout the world in the inventions and improvements in a patent document entitled:

ROUTING SQL STATEMENTS TO ELASTIC COMPUTE NODES USING WORKLOAD CLASS

which is found in the:

US patent application filed on: March 30, 2021

under Application No. 17/217,412

I authorize and request the attorneys of record or the attorney filing the application to insert into this assignment the filing date and serial number of the application when known. This assignment includes the foregoing patent application or patent, as well as continuations and divisionals of said application, all legal equivalents in any country, and all patents issuing from such legal equivalents; all patents, utility models, and design registrations granted by any jurisdiction for any of said inventions and improvements; and the right to claim priority based on the filing date of the foregoing patent application or patent under the International Convention for the Protection of Industrial Property, the Patent Cooperation Treaty, the European Patent Convention, and all other treaties of like purposes. I authorize the Assignee to apply in all countries in my name or in its own name for patents, utility models, and design registrations and like rights of exclusion and for inventors' certificates for said inventions and improvements. I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into that would conflict with this assignment. I hereby state and agree that no assignment, sale, agreement, or encumbrance has been or will be made or entered into that would conflict with this assignment. I further agree for myself and my heirs, legal representatives, and assigns to provide to the Assignee promptly upon its request and at its expense all pertinent facts and documents relating to any of said inventions and improvements or said patents and legal equivalents as may be known and accessible to me and to testify as to the same in any interference, litigation, or proceeding relating thereto; and I agree promptly to perform such lawful acts and to sign such further applications, assignments, statements, and other lawful documents as the Assignee may reasonably request to effectuate fully this assignment.

Inventor's Signature: DocuSigned by: Jaeyoung Choi 31955D21E755427... 3/30/2021

Jaeyoung Choi

Attorney Dkt. No. 8880-105854-01 / 200879US01

ASSIGNMENT

For valuable consideration, I, **Deok Hoe Kim,**

hereby assign to

SAP SE, a corporation of Europe having a place of business at Dietmar-Hopp-Allee 16, 69190 Walldorf, Germany

and its successors, and assigns (collectively, the ASSIGNEE) my entire right, title and interest throughout the world in the inventions and improvements in a patent document entitled:

ROUTING SQL STATEMENTS TO ELASTIC COMPUTE NODES USING WORKLOAD CLASS

which is found in the:

US patent application filed on: March 30, 2021

under Application No. 17/217,412

I authorize and request the attorneys of record or the attorney filing the application to insert into this assignment the filing date and serial number of the application when known. This assignment includes the foregoing patent application or patent, as well as continuations and divisionals of said application, all legal equivalents in any country, and all patents issuing from such legal equivalents; all patents, utility models, and design registrations granted by any jurisdiction for any of said inventions and improvements; and the right to claim priority based on the filing date of the foregoing patent application or patent under the International Convention for the Protection of Industrial Property, the Patent Cooperation Treaty, the European Patent Convention, and all other treaties of like purposes. I authorize the Assignee to apply in all countries in my name or in its own name for patents, utility models, and design registrations and like rights of exclusion and for inventors' certificates for said inventions and improvements. I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into that would conflict with this assignment. I hereby state and agree that no assignment, sale, agreement, or encumbrance has been or will be made or entered into that would conflict with this assignment. I further agree for myself and my heirs, legal representatives, and assigns to provide to the Assignee promptly upon its request and at its expense all pertinent facts and documents relating to any of said inventions and improvements or said patents and legal equivalents as may be known and accessible to me and to testify as to the same in any interference, litigation, or proceeding relating thereto; and I agree promptly to perform such lawful acts and to sign such further applications, assignments, statements, and other lawful documents as the Assignee may reasonably request to effectuate fully this assignment.

Inventor's Signature:

DocuSigned by:
Deokhoe Kim
064F883EE9DC478...

3/29/2021

Deok Hoe Kim

Attorney Dkt. No. 8880-105854-01 / 200879US01

ASSIGNMENT

For valuable consideration, I, **Kyu Hwan Kim,**

hereby assign to

SAP SE, a corporation of Europe having a place of business at Dietmar-Hopp-Allee 16, 69190 Walldorf, Germany

and its successors, and assigns (collectively, the ASSIGNEE) my entire right, title and interest throughout the world in the inventions and improvements in a patent document entitled:

ROUTING SQL STATEMENTS TO ELASTIC COMPUTE NODES USING WORKLOAD CLASS

which is found in the:

US patent application filed on: March 30, 2021

under Application No. 17/217,412

I authorize and request the attorneys of record or the attorney filing the application to insert into this assignment the filing date and serial number of the application when known. This assignment includes the foregoing patent application or patent, as well as continuations and divisionals of said application, all legal equivalents in any country, and all patents issuing from such legal equivalents; all patents, utility models, and design registrations granted by any jurisdiction for any of said inventions and improvements; and the right to claim priority based on the filing date of the foregoing patent application or patent under the International Convention for the Protection of Industrial Property, the Patent Cooperation Treaty, the European Patent Convention, and all other treaties of like purposes. I authorize the Assignee to apply in all countries in my name or in its own name for patents, utility models, and design registrations and like rights of exclusion and for inventors' certificates for said inventions and improvements. I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into that would conflict with this assignment. I hereby state and agree that no assignment, sale, agreement, or encumbrance has been or will be made or entered into that would conflict with this assignment. I further agree for myself and my heirs, legal representatives, and assigns to provide to the Assignee promptly upon its request and at its expense all pertinent facts and documents relating to any of said inventions and improvements or said patents and legal equivalents as may be known and accessible to me and to testify as to the same in any interference, litigation, or proceeding relating thereto; and I agree promptly to perform such lawful acts and to sign such further applications, assignments, statements, and other lawful documents as the Assignee may reasonably request to effectuate fully this assignment.

Inventor's Signature: DocuSigned by:
84FE070ECEFB436... 3/29/2021

Kyu Hwan Kim

Attorney Dkt. No. 8880-105854-01 / 200879US01

ASSIGNMENT

For valuable consideration, I, **Chae Kwang Lee,**

hereby assign to

SAP SE, a corporation of Europe having a place of business at Dietmar-Hopp-Allee 16, 69190 Walldorf, Germany

and its successors, and assigns (collectively, the ASSIGNEE) my entire right, title and interest throughout the world in the inventions and improvements in a patent document entitled:

ROUTING SQL STATEMENTS TO ELASTIC COMPUTE NODES USING WORKLOAD CLASS

which is found in the:

US patent application filed on: March 30, 2021

under Application No. 17/217,412

I authorize and request the attorneys of record or the attorney filing the application to insert into this assignment the filing date and serial number of the application when known. This assignment includes the foregoing patent application or patent, as well as continuations and divisionals of said application, all legal equivalents in any country, and all patents issuing from such legal equivalents; all patents, utility models, and design registrations granted by any jurisdiction for any of said inventions and improvements; and the right to claim priority based on the filing date of the foregoing patent application or patent under the International Convention for the Protection of Industrial Property, the Patent Cooperation Treaty, the European Patent Convention, and all other treaties of like purposes. I authorize the Assignee to apply in all countries in my name or in its own name for patents, utility models, and design registrations and like rights of exclusion and for inventors' certificates for said inventions and improvements. I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into that would conflict with this assignment. I hereby state and agree that no assignment, sale, agreement, or encumbrance has been or will be made or entered into that would conflict with this assignment. I further agree for myself and my heirs, legal representatives, and assigns to provide to the Assignee promptly upon its request and at its expense all pertinent facts and documents relating to any of said inventions and improvements or said patents and legal equivalents as may be known and accessible to me and to testify as to the same in any interference, litigation, or proceeding relating thereto; and I agree promptly to perform such lawful acts and to sign such further applications, assignments, statements, and other lawful documents as the Assignee may reasonably request to effectuate fully this assignment.

DocuSigned by:

Inventor's Signature: E0357B7C89A9492... 3/29/2021

Chae Kwang Lee

Attorney Dkt. No. 8880-105854-01 / 200879US01

ASSIGNMENT

For valuable consideration, I, **Jane Jung Lee,**

hereby assign to

SAP SE, a corporation of Europe having a place of business at Dietmar-Hopp-Allee 16, 69190 Walldorf, Germany

and its successors, and assigns (collectively, the ASSIGNEE) my entire right, title and interest throughout the world in the inventions and improvements in a patent document entitled:

ROUTING SQL STATEMENTS TO ELASTIC COMPUTE NODES USING WORKLOAD CLASS

which is found in the:

US patent application filed on: March 30, 2021

under Application No. 17/217,412

I authorize and request the attorneys of record or the attorney filing the application to insert into this assignment the filing date and serial number of the application when known. This assignment includes the foregoing patent application or patent, as well as continuations and divisionals of said application, all legal equivalents in any country, and all patents issuing from such legal equivalents; all patents, utility models, and design registrations granted by any jurisdiction for any of said inventions and improvements; and the right to claim priority based on the filing date of the foregoing patent application or patent under the International Convention for the Protection of Industrial Property, the Patent Cooperation Treaty, the European Patent Convention, and all other treaties of like purposes. I authorize the Assignee to apply in all countries in my name or in its own name for patents, utility models, and design registrations and like rights of exclusion and for inventors' certificates for said inventions and improvements. I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into that would conflict with this assignment. I hereby state and agree that no assignment, sale, agreement, or encumbrance has been or will be made or entered into that would conflict with this assignment. I further agree for myself and my heirs, legal representatives, and assigns to provide to the Assignee promptly upon its request and at its expense all pertinent facts and documents relating to any of said inventions and improvements or said patents and legal equivalents as may be known and accessible to me and to testify as to the same in any interference, litigation, or proceeding relating thereto; and I agree promptly to perform such lawful acts and to sign such further applications, assignments, statements, and other lawful documents as the Assignee may reasonably request to effectuate fully this assignment.

Inventor's Signature: DocuSigned by: Jane Jung Lee 2B0F1373A7E940C... 3/29/2021

Jane Jung Lee

Attorney Dkt. No. 8880-105854-01 / 200879US01

ASSIGNMENT

For valuable consideration, I, **Juchang Lee,**

hereby assign to

SAP SE, a corporation of Europe having a place of business at Dietmar-Hopp-Allee 16, 69190 Walldorf, Germany

and its successors, and assigns (collectively, the ASSIGNEE) my entire right, title and interest throughout the world in the inventions and improvements in a patent document entitled:

ROUTING SQL STATEMENTS TO ELASTIC COMPUTE NODES USING WORKLOAD CLASS

which is found in the:

US patent application filed on: March 30, 2021

under Application No. 17/217,412

I authorize and request the attorneys of record or the attorney filing the application to insert into this assignment the filing date and serial number of the application when known. This assignment includes the foregoing patent application or patent, as well as continuations and divisionals of said application, all legal equivalents in any country, and all patents issuing from such legal equivalents; all patents, utility models, and design registrations granted by any jurisdiction for any of said inventions and improvements; and the right to claim priority based on the filing date of the foregoing patent application or patent under the International Convention for the Protection of Industrial Property, the Patent Cooperation Treaty, the European Patent Convention, and all other treaties of like purposes. I authorize the Assignee to apply in all countries in my name or in its own name for patents, utility models, and design registrations and like rights of exclusion and for inventors' certificates for said inventions and improvements. I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into that would conflict with this assignment. I hereby state and agree that no assignment, sale, agreement, or encumbrance has been or will be made or entered into that would conflict with this assignment. I further agree for myself and my heirs, legal representatives, and assigns to provide to the Assignee promptly upon its request and at its expense all pertinent facts and documents relating to any of said inventions and improvements or said patents and legal equivalents as may be known and accessible to me and to testify as to the same in any interference, litigation, or proceeding relating thereto; and I agree promptly to perform such lawful acts and to sign such further applications, assignments, statements, and other lawful documents as the Assignee may reasonably request to effectuate fully this assignment.

Inventor's Signature: DocuSigned by: Juchang Lee A938672EF2594F2... 3/30/2021

Juchang Lee